



MICROMACHINED BULK WAVE ACOUSTIC BANDGAP DEVICES

**14th International Conference on Solid-State
Sensors, Actuators, and Microsystems**

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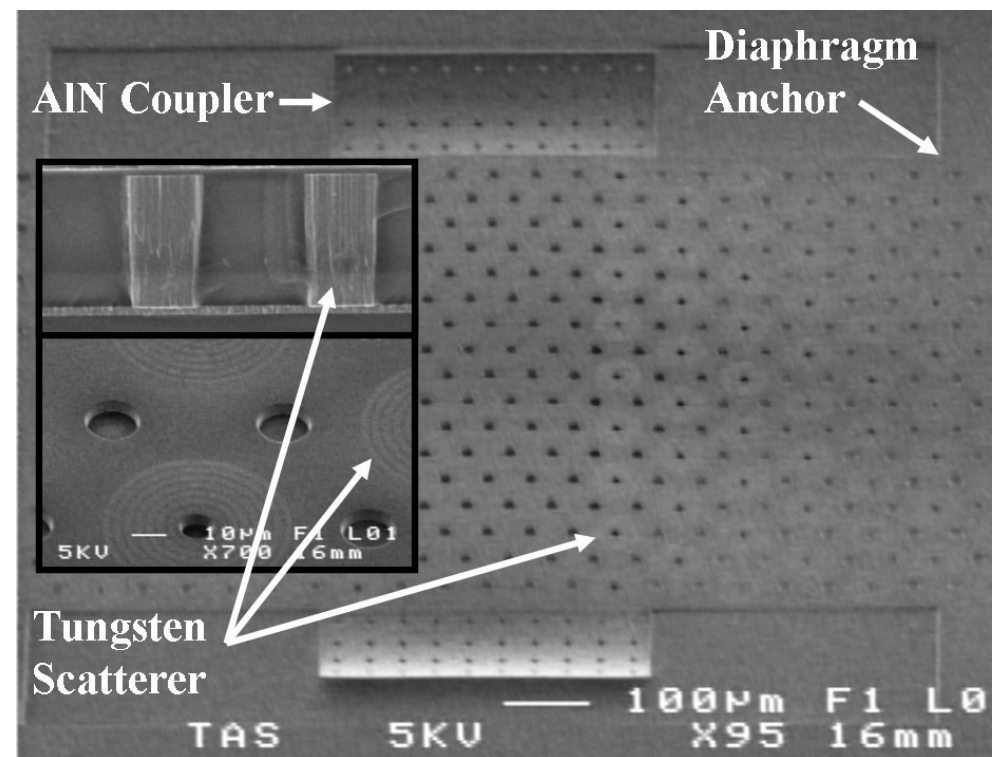
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**Senior Member of Technical Staff
Sandia National Laboratories**



Outline

- Background
 - What is an acoustic bandgap (ABG) device or acoustic crystal?
- Design
 - Materials
 - Topology
 - Couplers
- Fabrication
- Measured Results
- Acoustic Bandgap Waveguides
- Applications and Future Directions



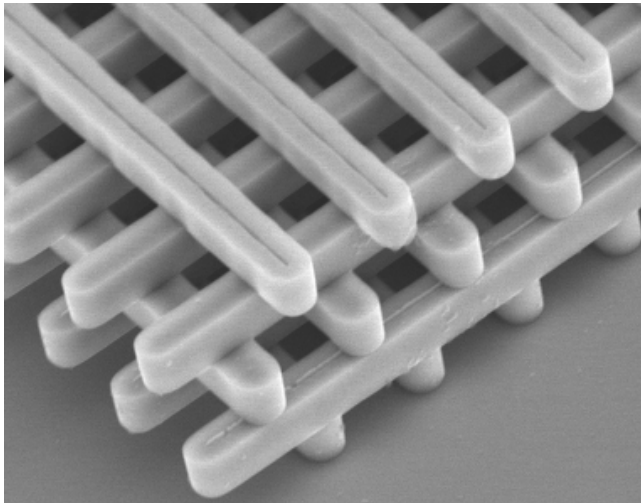
Triangular lattice ABG waveguide
operating at 30 MHz



Acoustic vs. Photonic Crystals

Photonic Bandgap (PBG)

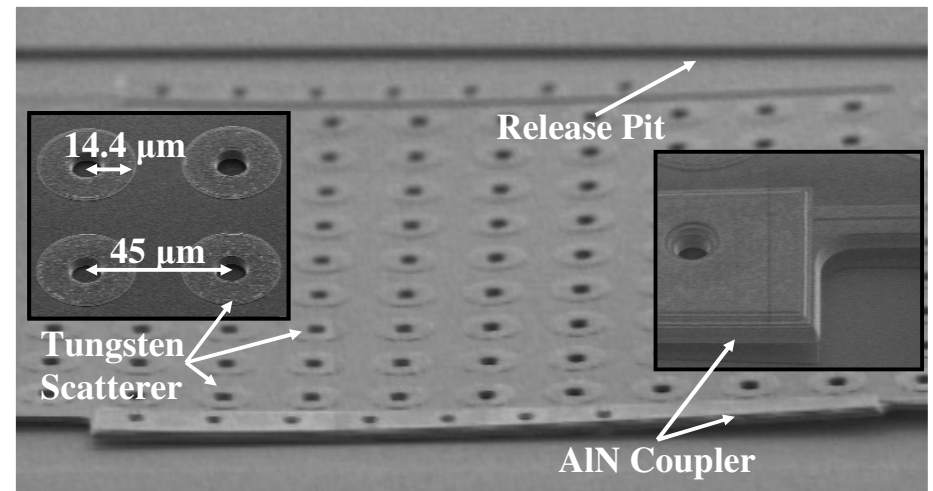
- High refractive index scatterer in low refractive index matrix
- Network topology
- 3D required for full control
- Integration of lasers and photodetectors problematic
- 2nd order coupled vector equations with 2 polarizations
- Inherently linear



3D woodpile photonic crystal

Acoustic Bandgap (ABG)

- High acoustic impedance scatterer in low acoustic impedance matrix
- Cermet topology
- Full control in 2D (vacuum)
- Micromachined integration of piezoelectric or capacitive couplers
- 2nd order coupled vector equations with 3 polarizations
- Inherently non-linear



2D acoustic crystal



ABG Materials Selection

Matrix

- Low acoustic impedance
- Low density
- High velocity
- High-Q

Matrix Material	Density (kg/m ³)	Velocity (km/s)	Z (MΩ)	Q
Polymers	1190	1.84	2.2	$\approx 10^2$
AlN	3230	9.77	31.5	$> 10^3$
Si	2330	8.52	19.8	$> 10^5$
SiO ₂	2200	5.84	12.8	$> 10^3$

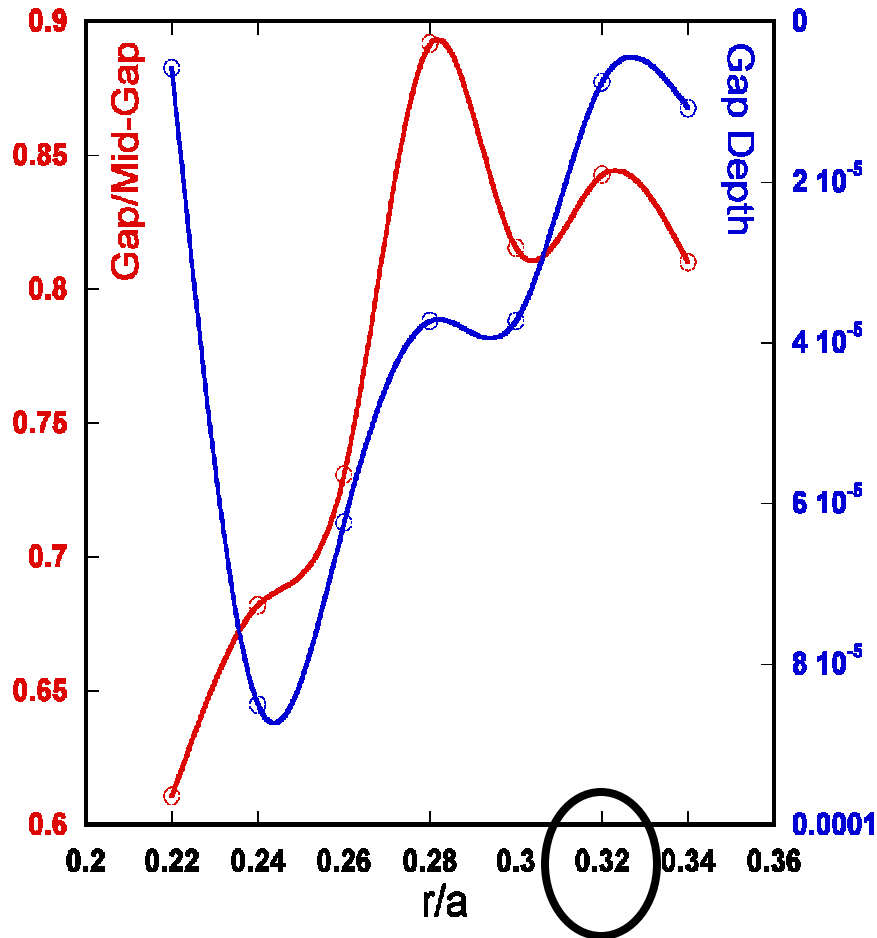
Inclusion

- High acoustic impedance
- High density
- High velocity
- High-Q

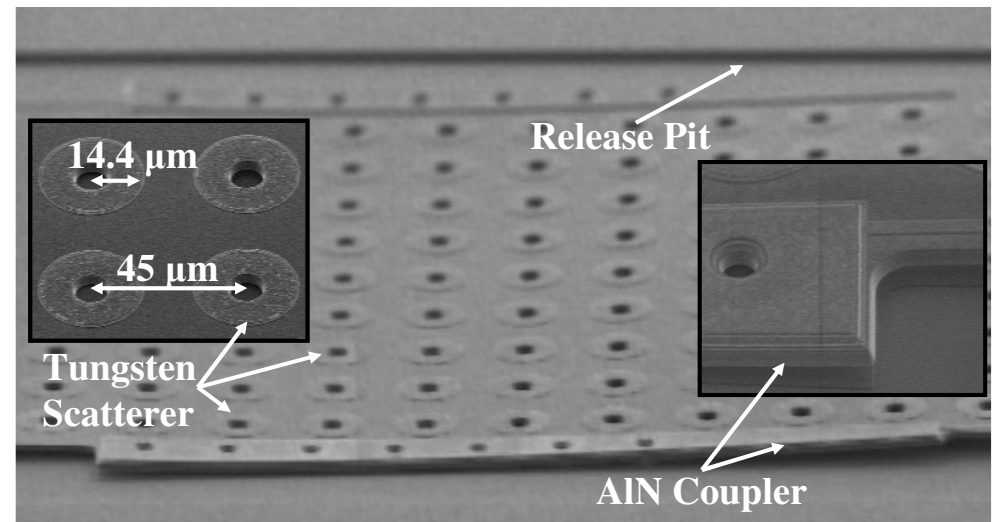
Inclusion Material	Density (kg/m ³)	Velocity (km/s)	Z (MΩ)	Q
Moly	10,300	5.7	59	$> 10^5$
Pt	21,440	2.8	60	$> 10^4$
W Carbide	15,800	6.6	104	?
W	19,300	4.6	89	$> 10^5$

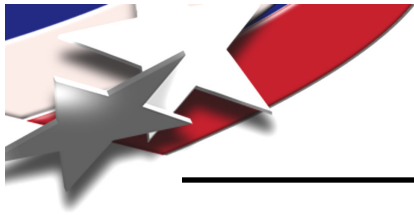


Fabrication at Higher Frequency



Frequency (MHz)	Lattice Constant a (μm)	W Radius r (μm)
30 MHz	100 μm	32
67 MHz	45 μm	14.4
300 MHz	10 μm	3.2
3 GHz	1 μm	0.32



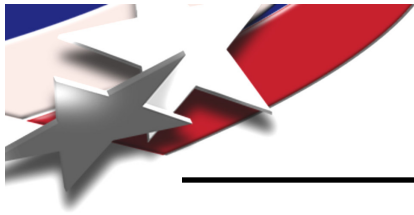


ABG Fabrication

- Deposit oxide etch-stop and silicon release layers
- Sputter deposit and pattern Al bottom interconnect layer
- PECVD SiO_2 low density, low impedance matrix material



■ Si ■ SiO_2 ■ Al



ABG Fabrication

- Etch holes in the oxide for scatterer formation, stop on Al
- CVD 1.2 μm of Tungsten (W)
- CMP Tungsten until it remains only in the etched oxide holes



□ Si □ SiO₂ □ Al □ W



ABG Fabrication

- Etch holes in the oxide to complete the scatterer
- CVD 1.2 μm of Tungsten (W)
- Tungsten CMP



□ Si □ SiO₂ □ Al □ W



ABG Fabrication

- Deposit and pattern Ti/TiN/Al bottom electrode (FWHM = 1.5°)
- Sputter deposit and pattern $0.75\text{ }\mu\text{m}$ AlN at $350\text{ }^\circ\text{C}$
- Deposit and pattern top Al electrode

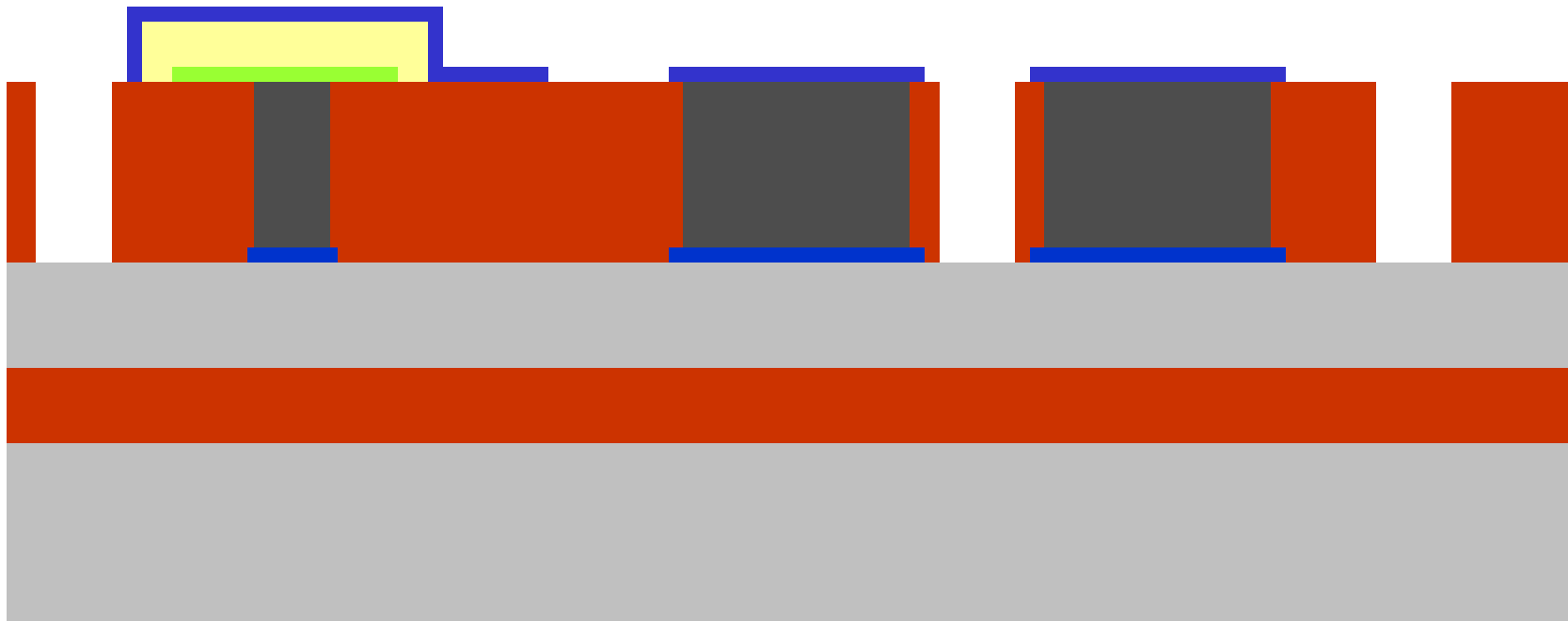


□ Si □ SiO₂ □ Al □ W □ Ti/TiN/Al □ AlN



ABG Fabrication

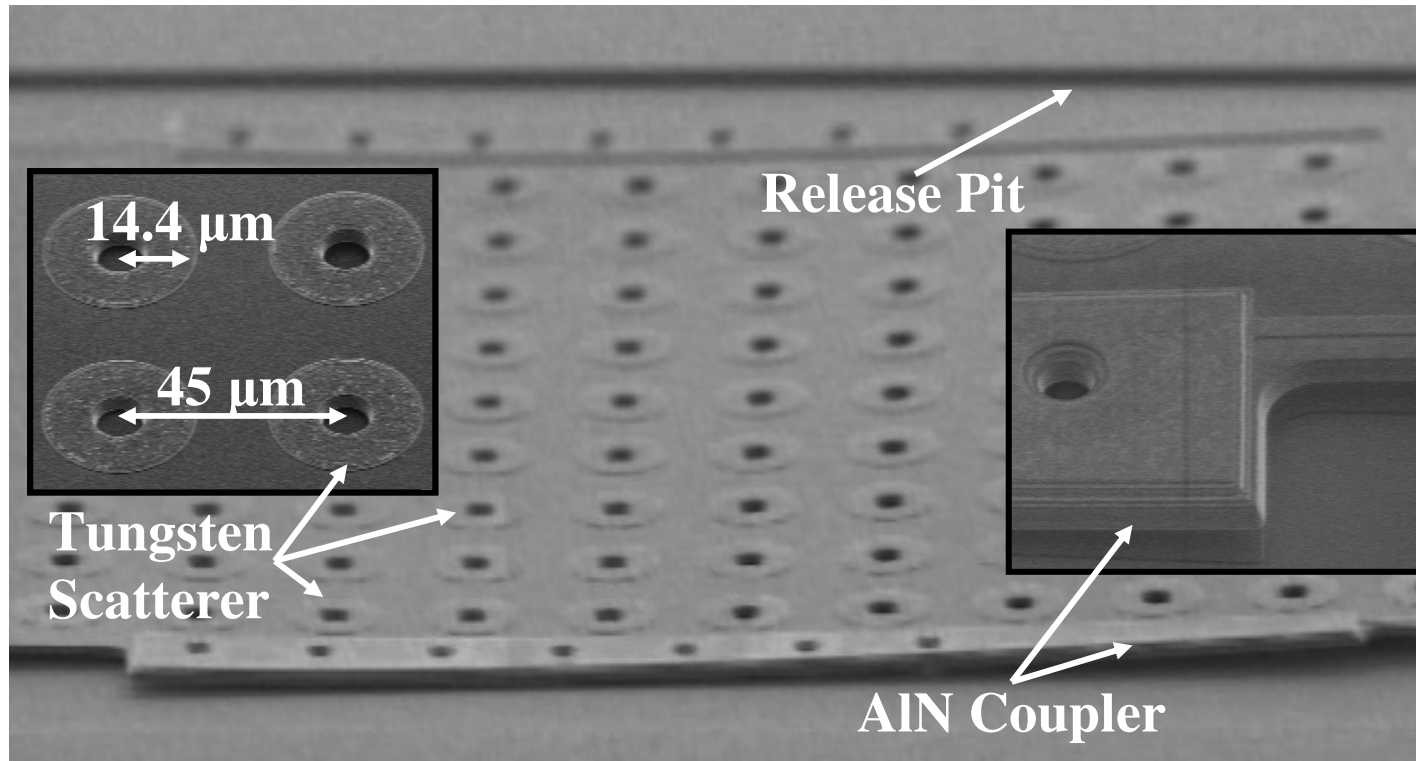
- Etch release holes through oxide to Si release layer
- Release in dry SF_6



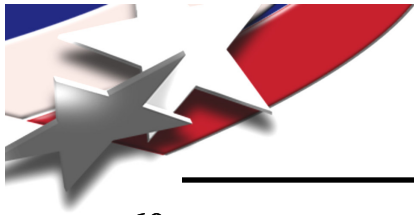
□ Si □ SiO_2 □ Al □ W □ Ti/TiN/Al □ AlN

ABG Fabrication

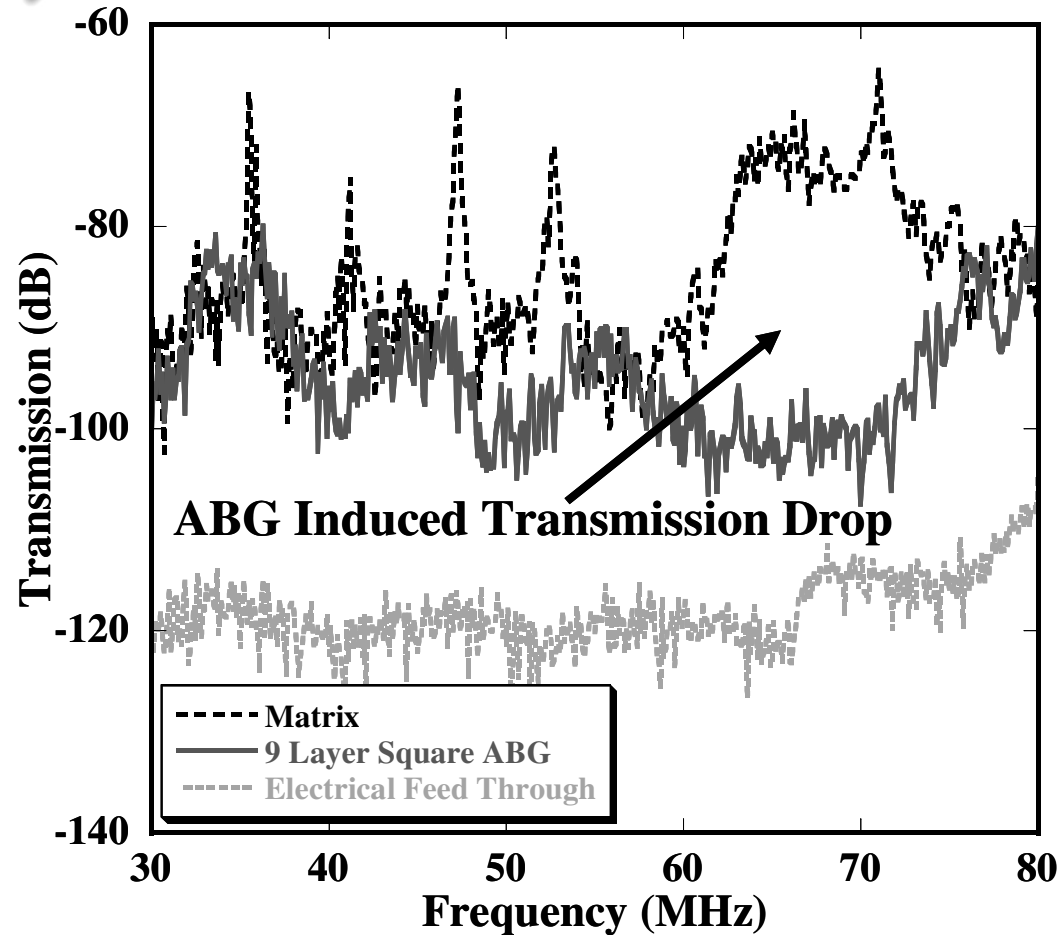
- 7 Levels (Post-CMOS Compatible)
- Tungsten ($\rho = 19,300 \text{ kg/m}^3$, $Z = 89 \text{ M}\Omega$)
- SiO_2 ($\rho = 2,200 \text{ kg/m}^3$, $Z = 13 \text{ M}\Omega$)
- Merged AlN and molded W processing



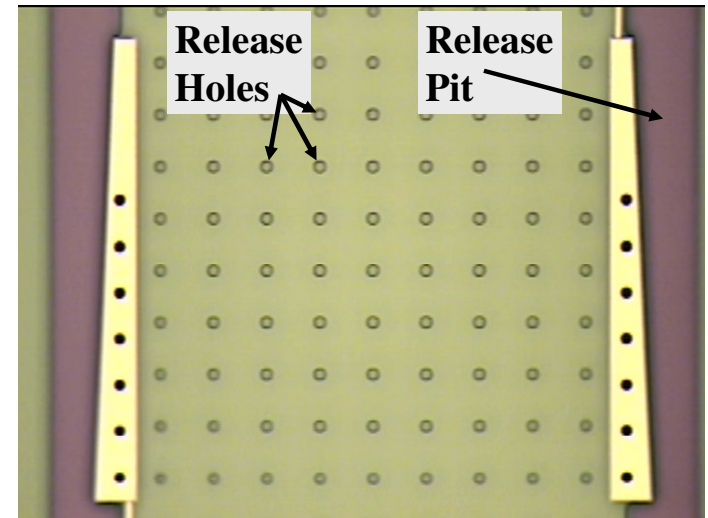
ABG with integrated AlN electro-acoustic couplers
centered at 67 MHz



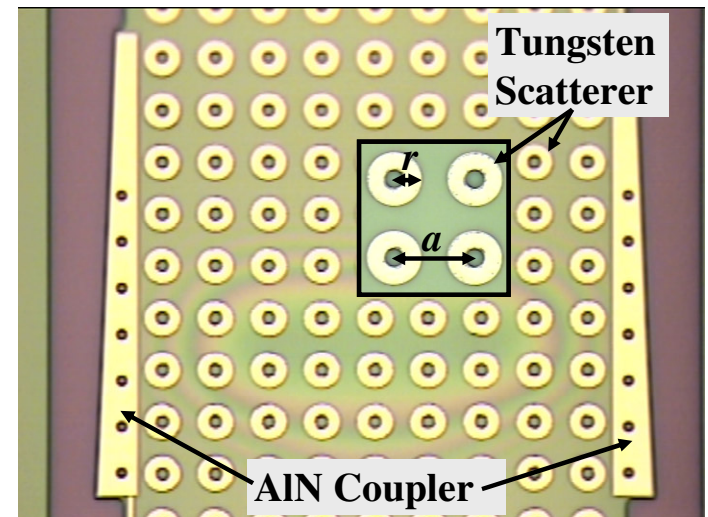
ABG Measured Results



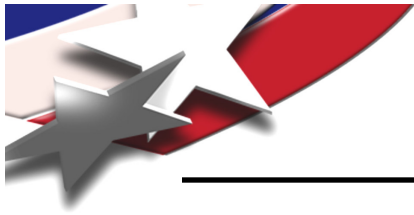
Measured transmission of the reference matrix membrane, 9-layer square lattice ABG, and the feed-through between two acoustically uncoupled pads



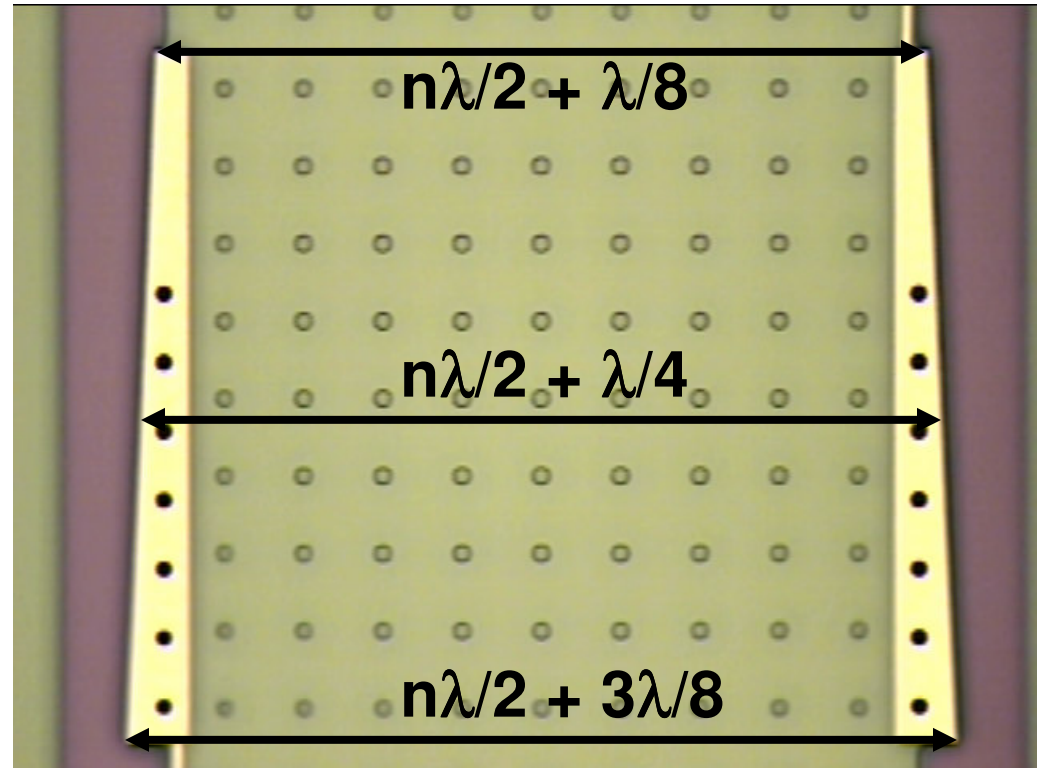
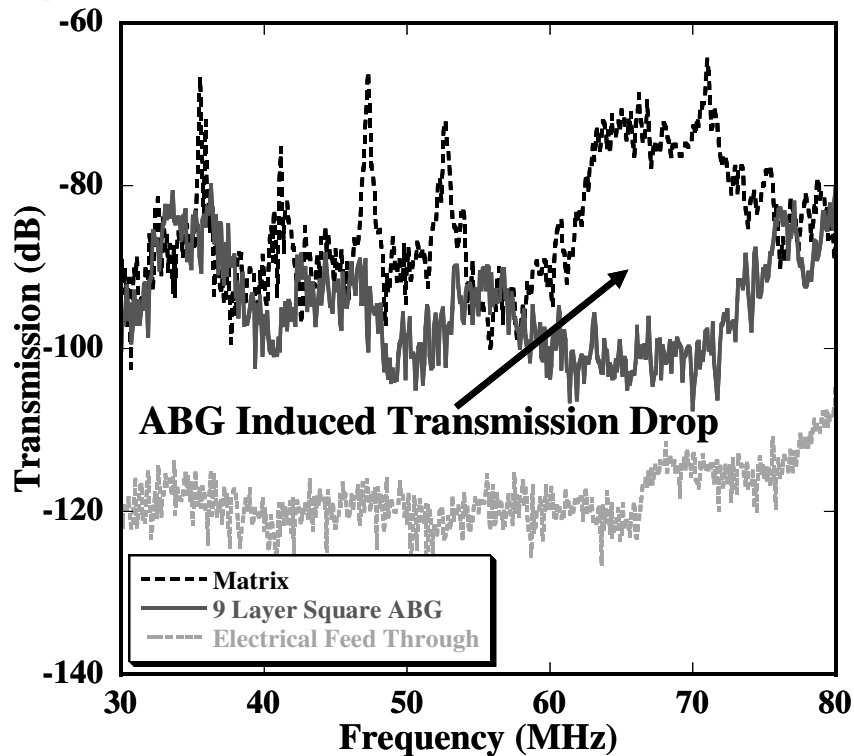
SiO₂ matrix with AlN couplers



Square lattice ABG



ABG Wideband Coupler Design



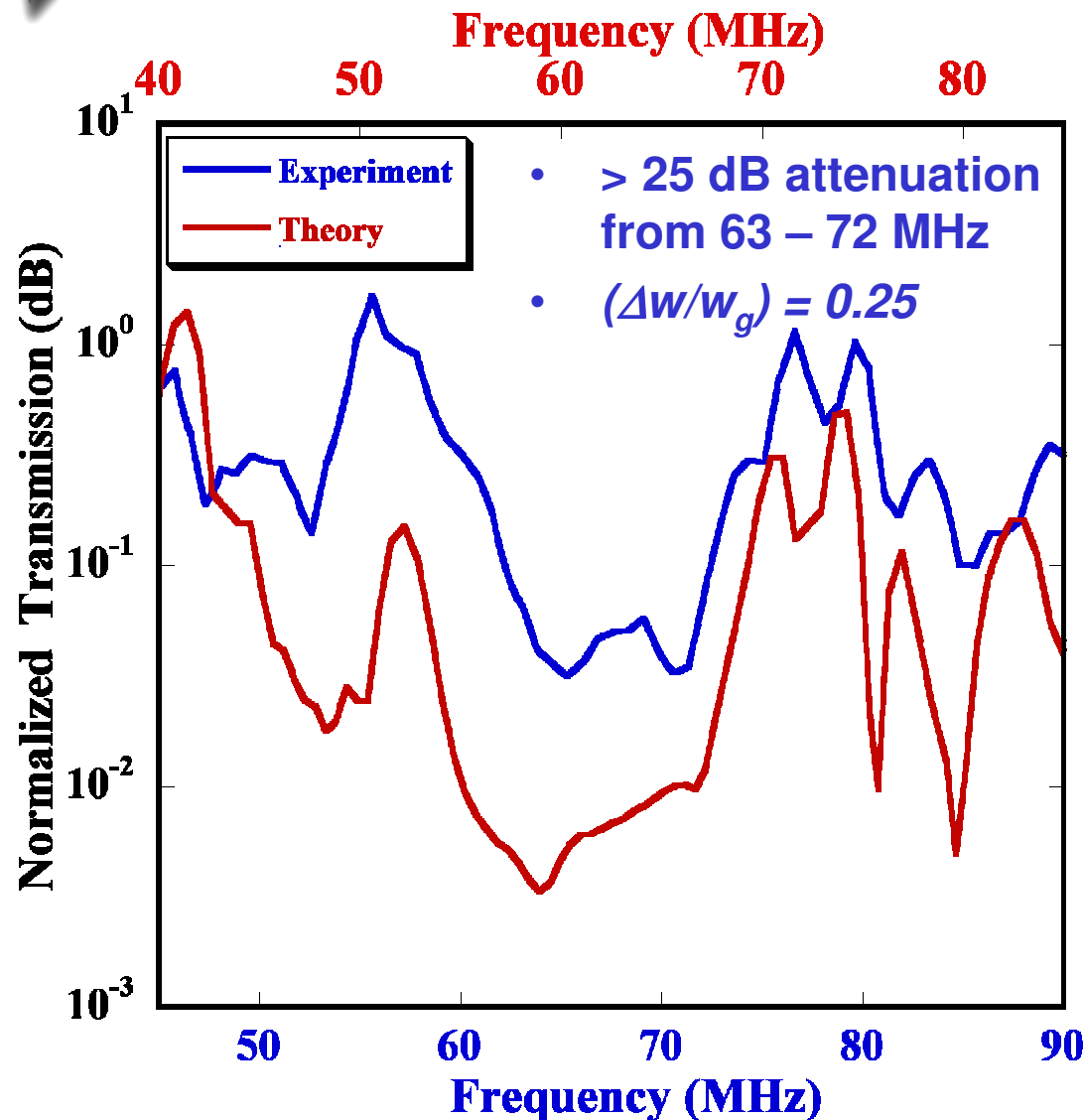
$$C_{\text{oxide}} = 5.8 \text{ km/s}$$

$$n = 10$$

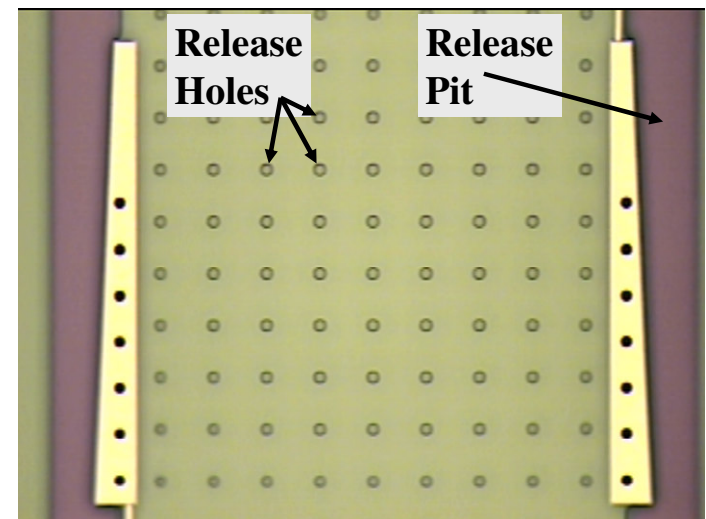
$$\lambda = 88 \mu\text{m}$$

$$f_0 = 66 \text{ MHz}$$

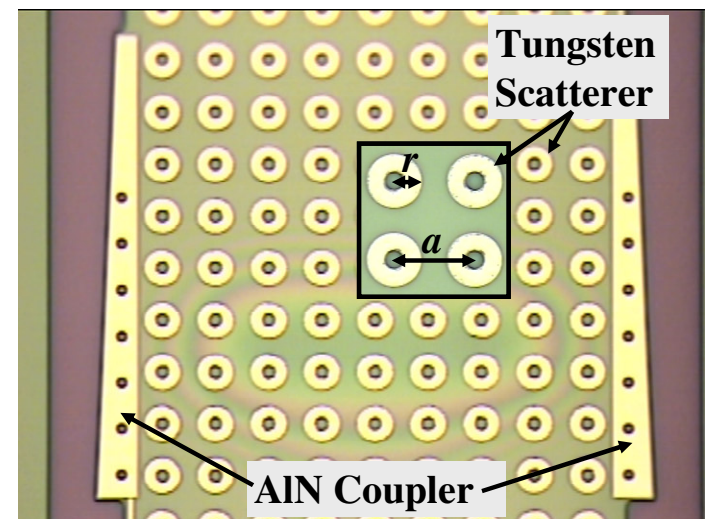
ABG Normalized Transmission



FDTD simulated and measured relative transmission for the square lattice ABG



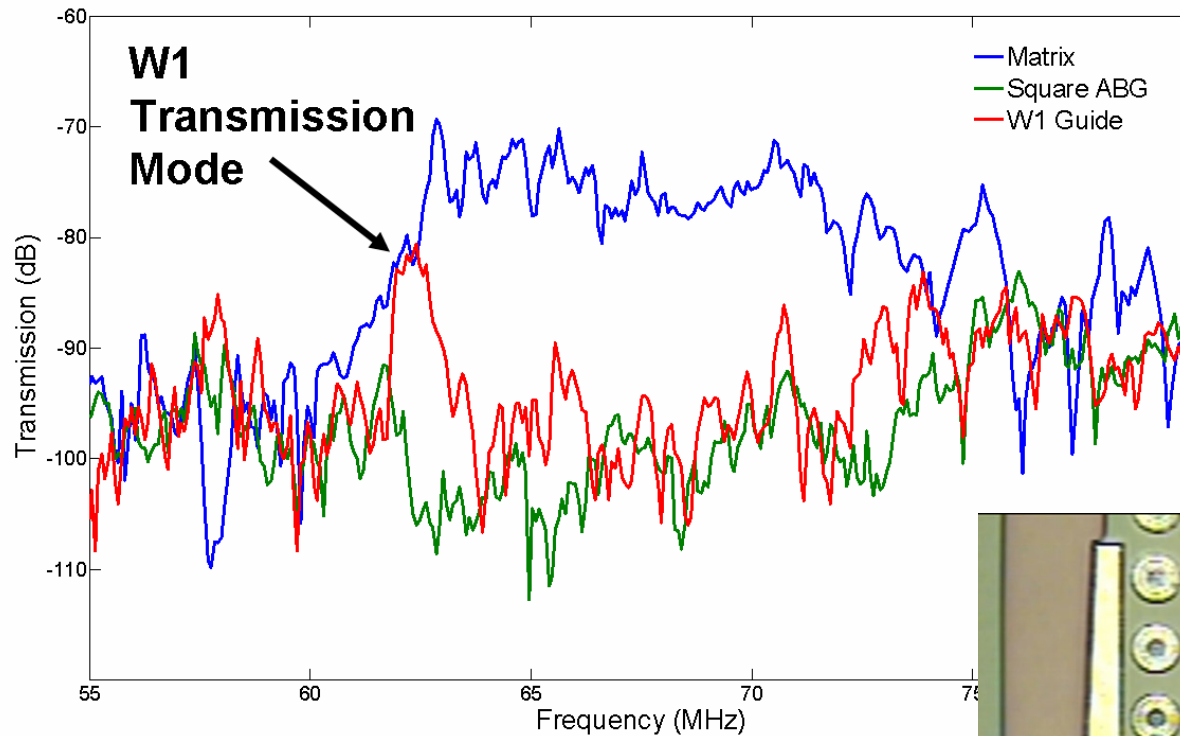
SiO₂ matrix with AlN couplers



Square lattice ABG

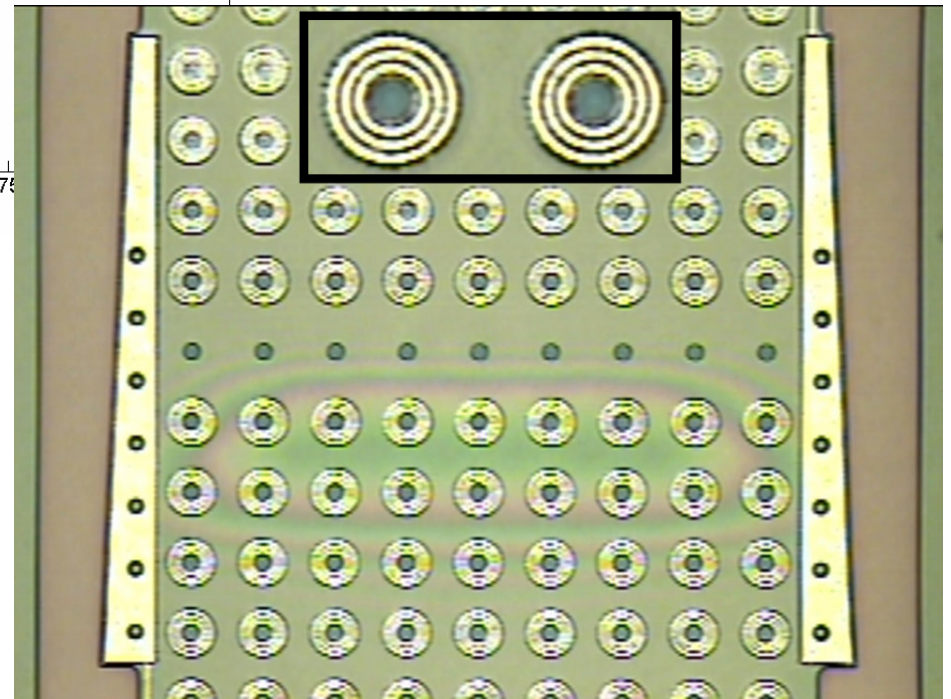


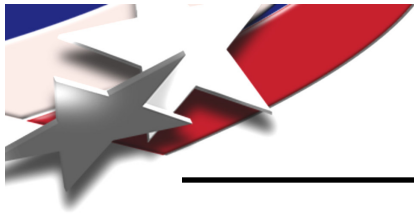
ABG W1 Waveguide



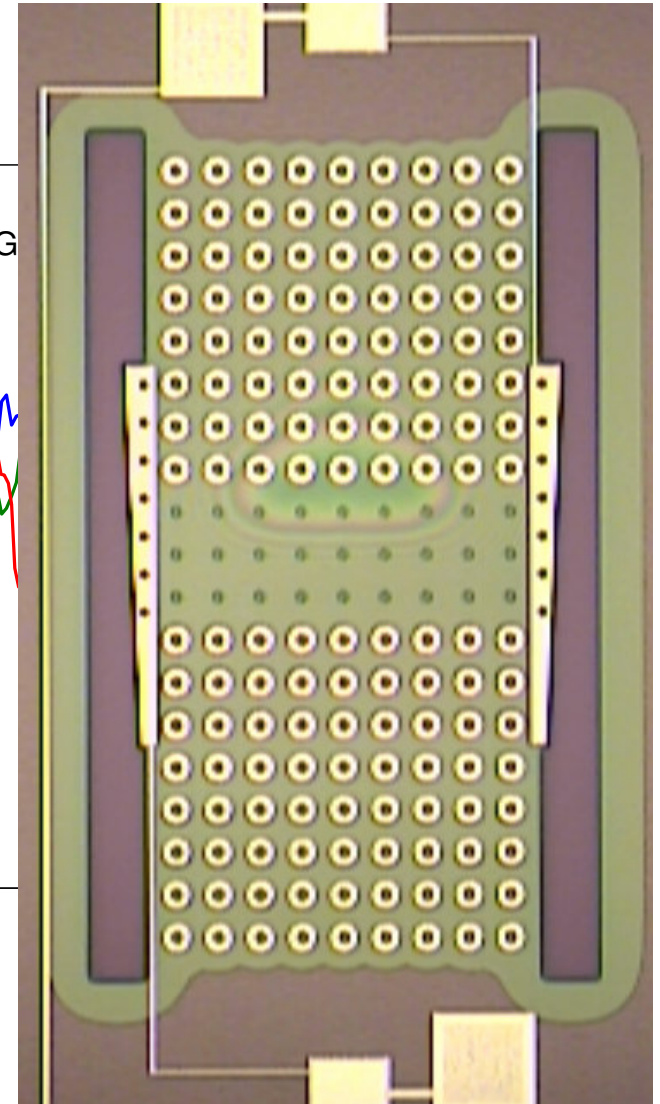
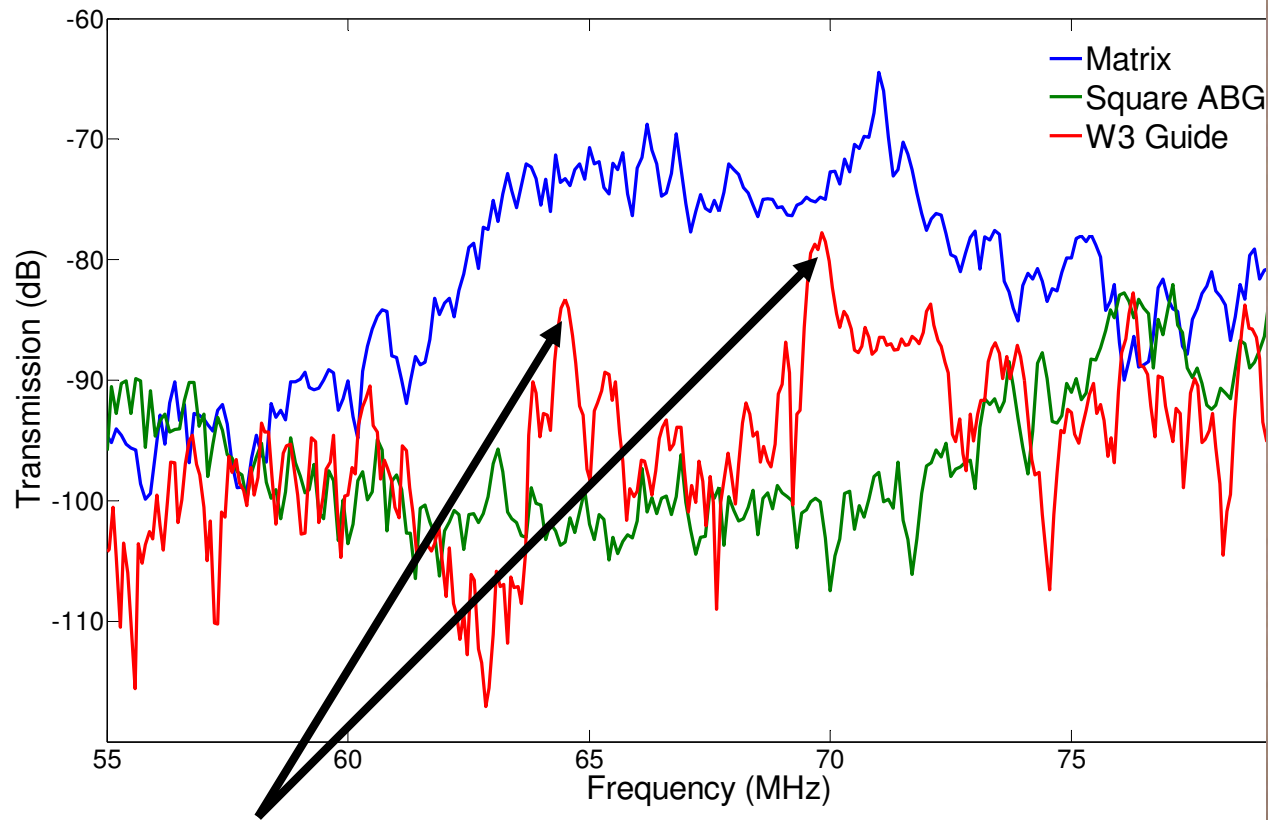
(Left) Measured response of a W1 waveguide showing 100% relative transmission at 62 MHz

(Right) Picture of an ABG W1 waveguide where 1 row of tungsten scatterers has been removed between the AlN couplers





ABG W3 Waveguide

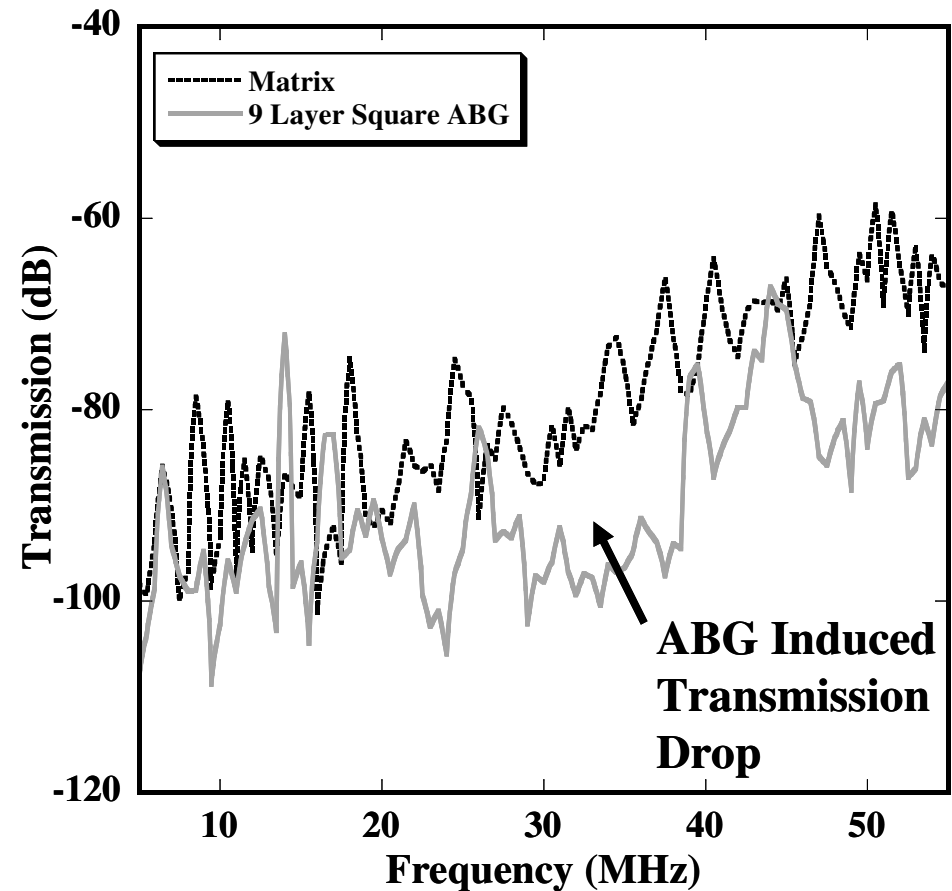


**Modes Propagating
in the Guide**



Potential Applications

- RF
 - High-Q Cavities
 - High Order Filters
 - Nonlinear Devices
- Bio
 - Cell Manipulation
 - Mass Sensing
- Ultrasound
 - Acoustic Focusing
- Nondestructive Testing
 - Acoustic Focusing
 - Crack Detection

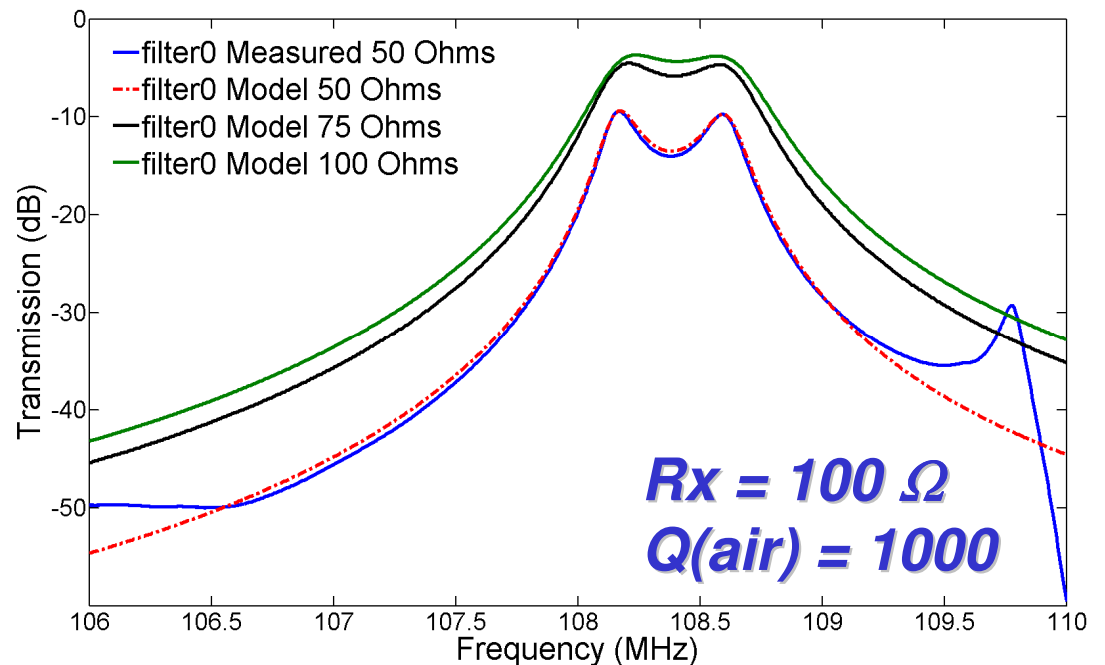
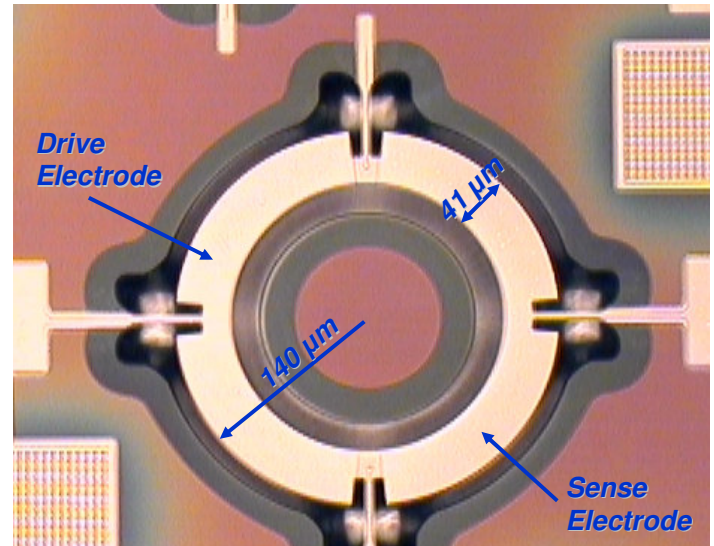


Transmission of a 33 MHz ABG



High-Q Cavities (Piezoelectric Devices)

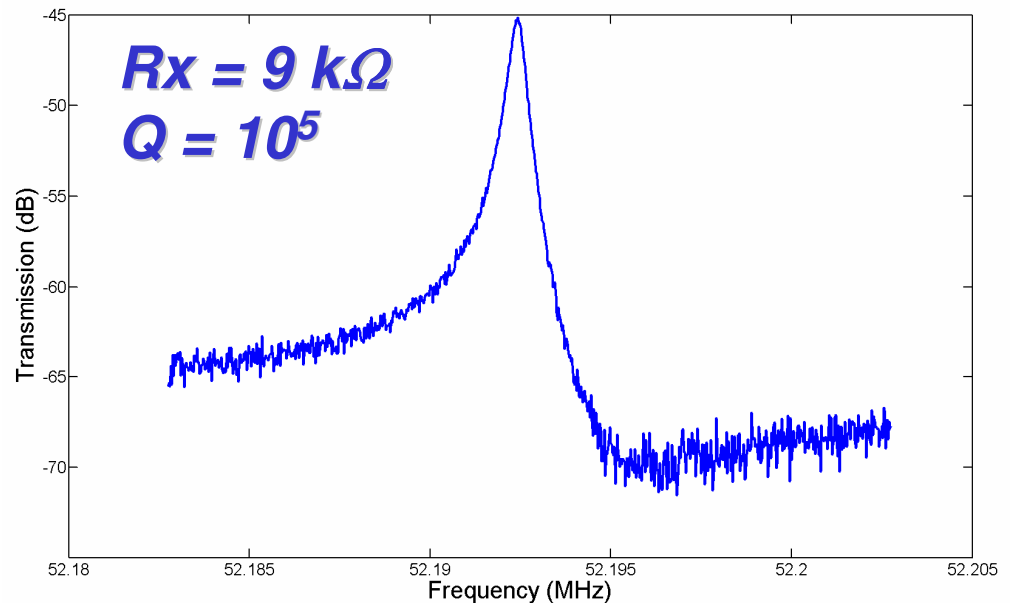
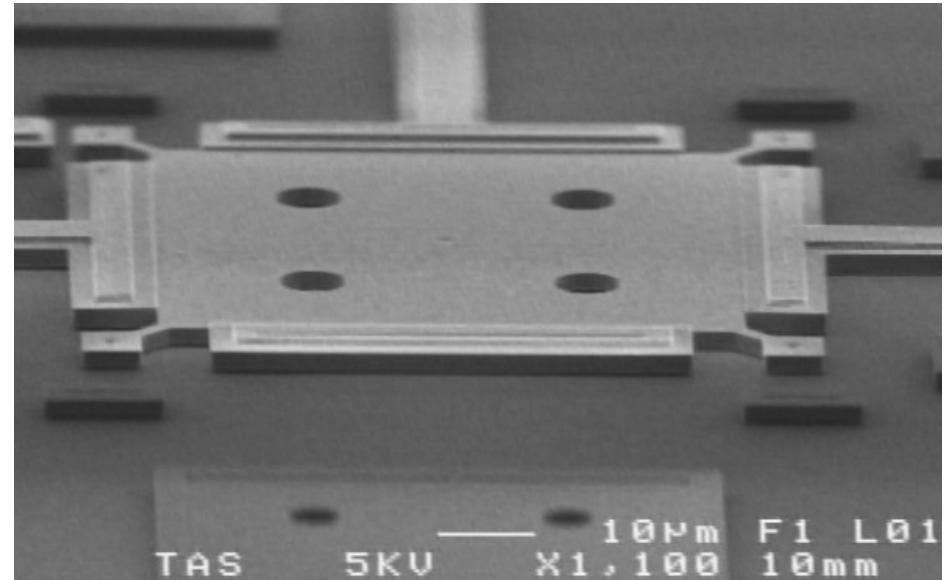
- Low insertion loss (impedance) filters because of the strong piezoelectric transduction
- Resonator is comprised of piezoelectric material
- Material damping limits Q to a few thousand
- Devices include SAW, FBAR, and AlN microresonator





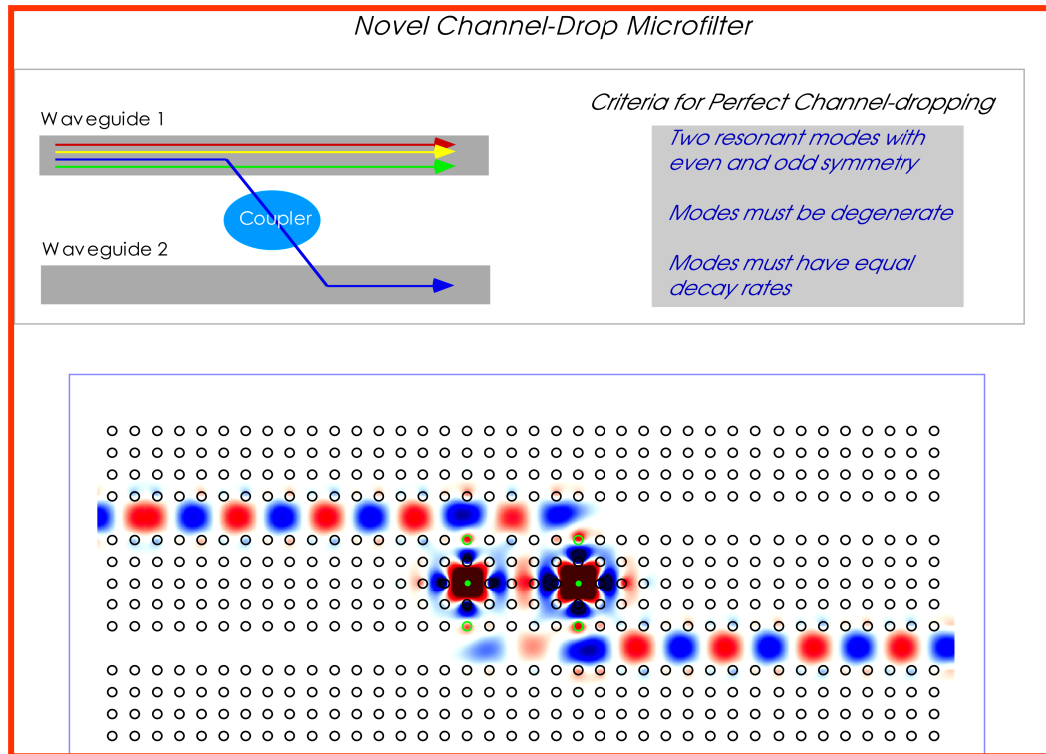
High-Q Cavities (Silicon Devices)

- High-Q derived from low material damping polysilicon
- Q's of a few 100,000 possible
- 2 orders of magnitude higher than piezoelectric materials
- High insertion loss (impedance) due to weak capacitive transduction
- Devices include polySi, SiGe, Ni and W microresonators





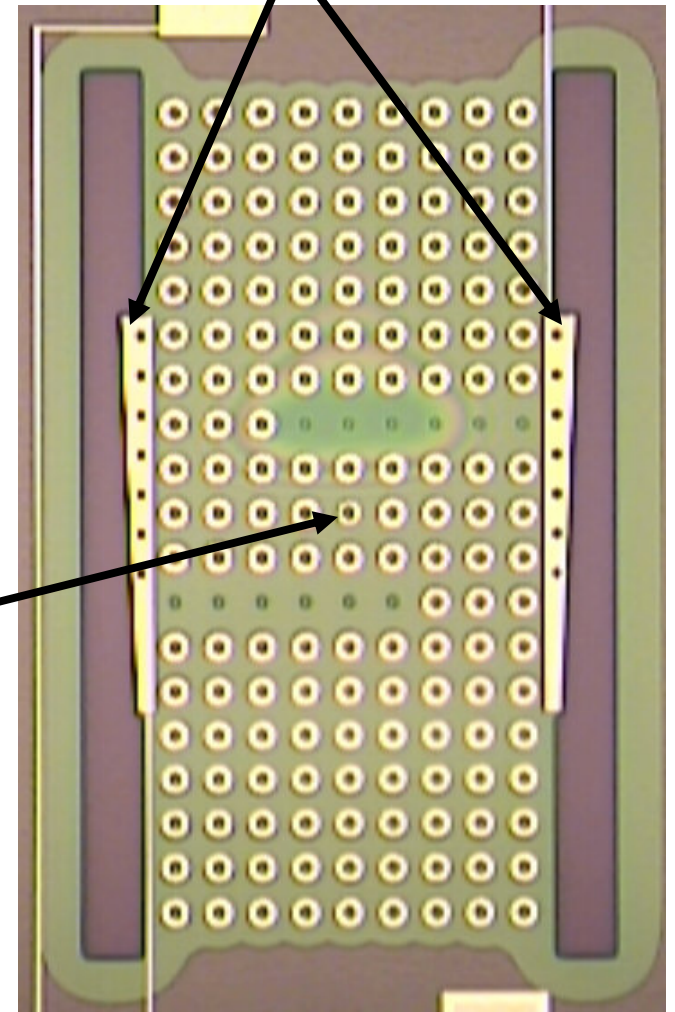
High-Q Cavities (ABG Devices)



- Cavities with $Q > 10^6$ reported for photonic crystals by altering ABG pitch (easier to control lithographically)

Cavity realized in High-Q ABG materials

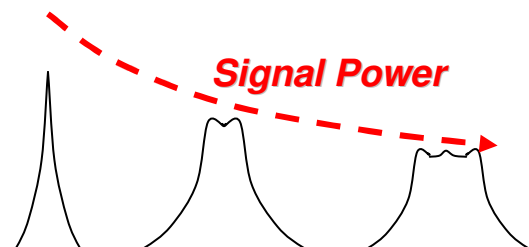
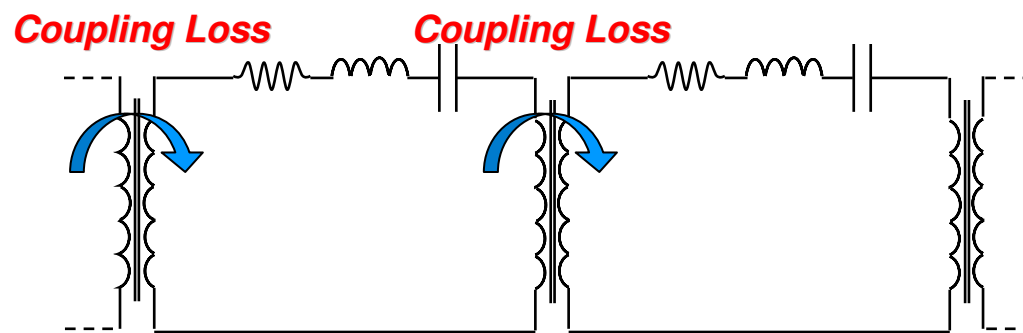
Piezoelectric Couplers (low insertion loss)





ABG for High-Order Filters

- Insertion loss is dominated by coupling from EM to acoustics
 - Once in the acoustic domain would like to stay there
- High order filters by mechanically or electrically coupling resonators
- FBAR can not achieve mechanical coupling » must electrically couple
- Mechanically coupled microresonators
 - Coupled by small beams requiring order of magnitude better lithographic control than the resonators themselves
 - Bandwidth and ripple hard to control » practical devices are electrically coupled



Analogue Signal Processing:

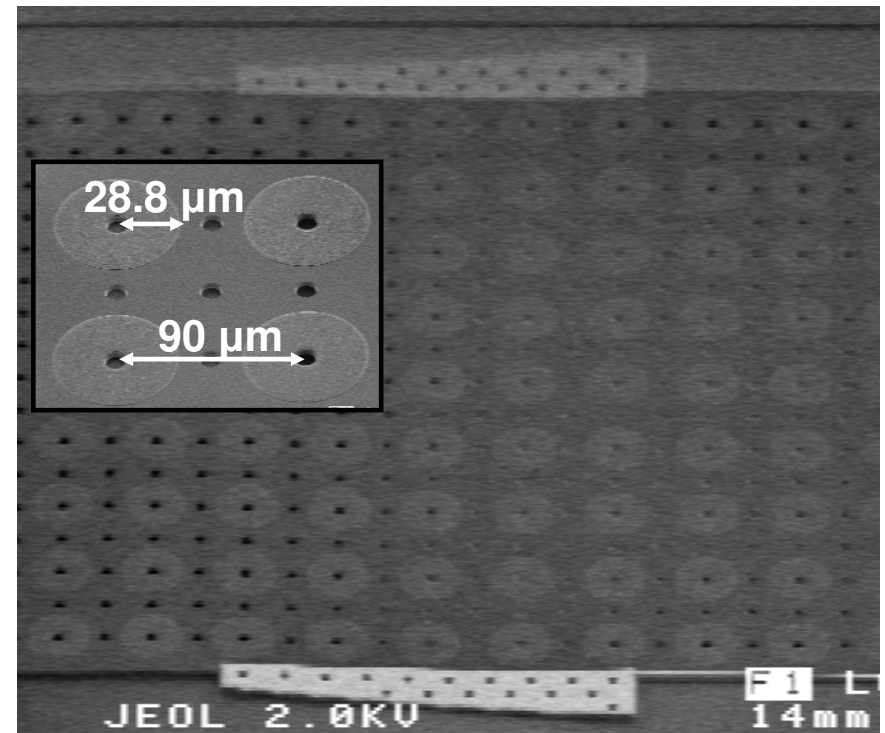
Cascaded insertion losses imply that once we are in the acoustic domain we would like to remain in it!

- ABG allows resonators to be coupled by waveguides
- Cavities realized by altering pitch
- High order, low loss filters and advanced signal processing

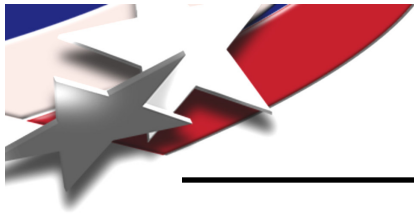


Conclusions

- Described Acoustic Bandgap Devices (ABGs)
- Design of ABGs
 - Materials, Topology, Couplers
- Fabrication
 - Post CMOS compatible AlN and W process
- Measured Results
 - > 25 dB ABG over ≈ 10 MHz @ 70 MHz
- Acoustic Bandgap Waveguides
 - W1 and W3 single and multi-mode waveguides
- Applications
 - RF, Bio, Ultrasound Nondestructive Testing



Square lattice ABG operating at 30 MHz



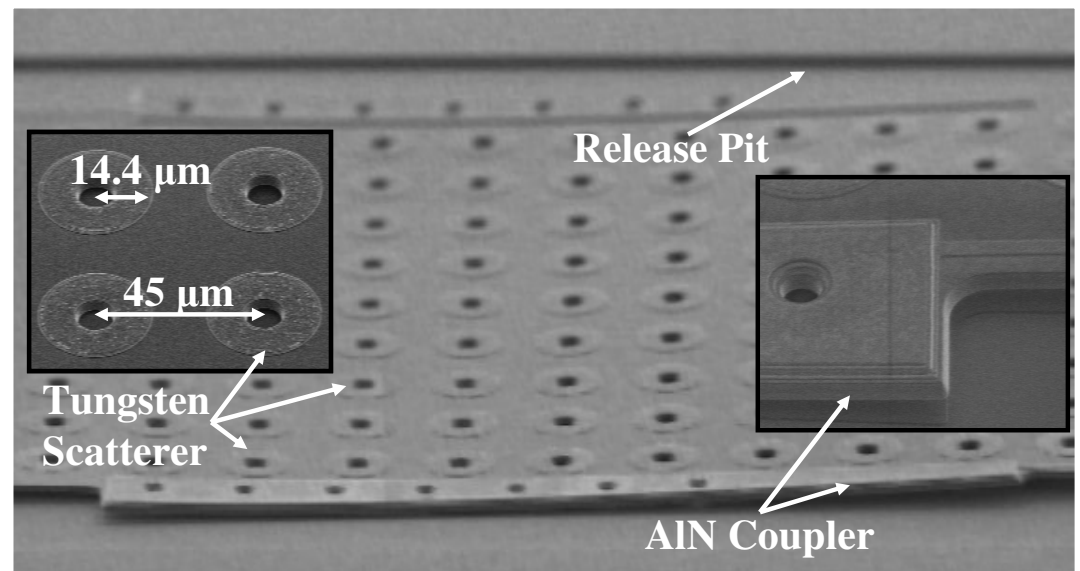
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